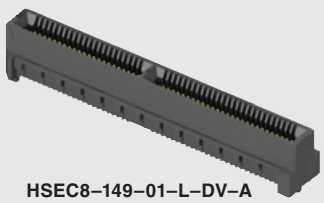
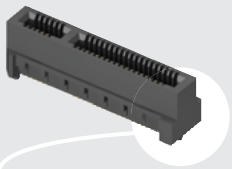
samtec

E.L.P.™
EXTENDED LIFE PRODUCT
10 year Mixed Flowing Gas with 30µ" Gold
Call Samtec for maximum mated cycles


HSEC8–149–01–L–DV–A

HSEC8–125–01–L–DV–A


(0.80 mm) .0315"

HSEC8-DV SERIES

VERTICAL EDGE RATE® CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-DV

Insulator Material: Black Liquid Crystal Polymer
Contact: BeCu
Plating: Au or Sn over 50µ" (1.27 µm) Ni
Current Rating: 2.8 A per pin (2 adjacent pins powered)
Operating Temp: -55°C to +125°C
Card Insertion Depth: (3.15 mm) .125" nominal
RoHS Compliant: Yes

Processing:

Lead–Free Solderable: Yes
SMT Lead Coplanarity: (0.10 mm) .004" max (10-60)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594
FILE NO: 090871_0_000

OTHER SOLUTIONS

- Standard high speed interface cards for 19 mm, 25 mm & 30 mm mated heights, single-ended & differential applications. See HSC8 Series.

ALSO AVAILABLE (MOQ Required)

- Guide rails
- Pass-through options
- Other platings
- Custom cards for low-cost stack height customization
- Samtec supplied card layout/artwork to make your own cards
- Specialty card shapes

Contact Samtec.

CABLE	CONNECTOR
ECDP–04	HSEC8–109–L2
ECDP–08	HSEC8–113–L2
ECDP–16	HSEC8–125–L2
ECDP–32	HSEC8–149–L2

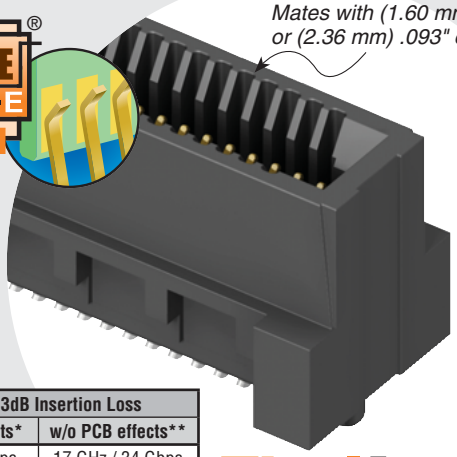
Notes:
While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

Some lengths, styles and options are non-standard, non-returnable.

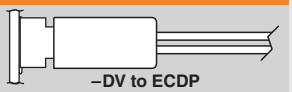
Mates with:
(1.60 mm) .062" card,
(2.36 mm) .093" card,
ECDP, HSC8

EDGE RATE® CONTACT

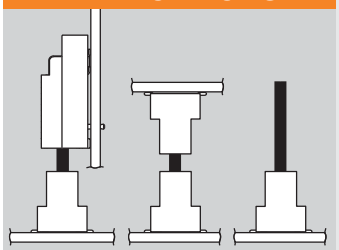
Mates with (1.60 mm) .062" or (2.36 mm) .093" cards



HIGH SPEED CABLE APPLICATIONS


–DV to ECDP

BOARD-TO-BOARD APPLICATIONS


–RA to –DV | –DV to –DV | PCB to –DV

HSEC8 7.98 mm Stack Height	Rated @ 3dB Insertion Loss	
	with PCB effects*	w/o PCB effects**
Single-Ended Signaling	8 GHz / 16 Gbps	17 GHz / 34 Gbps
Differential Pair Signaling	10.5 GHz / 21 Gbps	15.5 GHz / 31 Gbps

*Performance data includes effects of a non-optimized PCB.
**Test board losses de-embedded from performance data.

Complete test data available at www.samtec.com?HSEC8-DV or contact sig@samtec.com

Finalinch® CERTIFIED 28+ Gbps

HSEC8 – 1 – POSITIONS PER ROW – CARD THICKNESS – PLATING OPTION – DV – A – OTHER OPTION

09, 10, 13, 20, 25, 30, 37, 40, 49, 50, 60, 70, 80, 100
(13, 25, 49 only available with –L or –L2 option;
09 only available with –L2 option;
37 only available with –L option)

–01
= (1.60 mm) .062" thick card

–03
=(2.36 mm) .093" thick card

–L
= 10µ" (0.25 µm) Gold on contact, Matte Tin on tail

–S
= 30µ" (0.76 µm) Gold on contact, Matte Tin on tail

–K
= (7.01 mm) .276" DIA Polyimide Film Pick & Place Pad (with –01 card)
= (6.25 mm) .246" DIA Polyimide Film Pick & Place Pad (with –03 card)

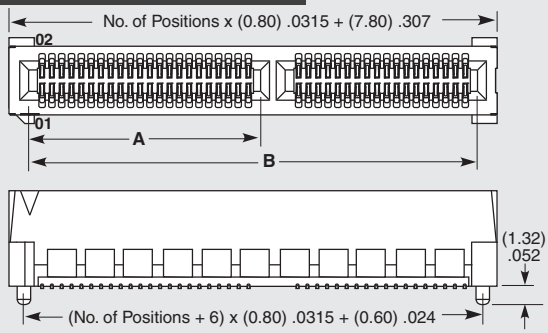
–BL
= Board Locks (40, 50, 60, 80 only) (Other sizes available. Contact Samtec.) (Weld tab standard)

–L
= Latching Option (13, 25, 37, 49 only) (Weld tab standard)

–L2
= ECDP Latching (09, 13, 25, 49 only) (For use with ECDP) (Weld tab standard)

–WT
= Weld tab

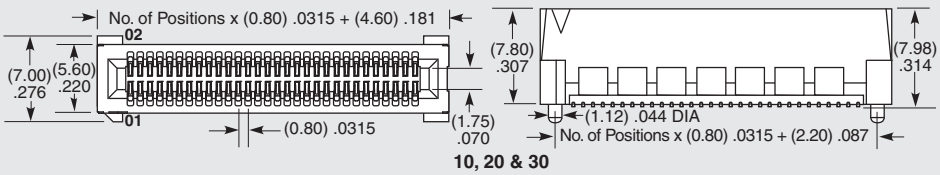
–TR
= Tape & Reel (09 - 70 only)



09, 13, 25, 37–100

POSITIONS PER ROW	A	B
09*†	(4.50) .177	(11.80) .465
13*†	(6.10) .240	(15.00) .591
25*†	(6.10) .240	(24.60) .969
37†	(18.10) .713	(34.20) 1.346
40	(18.90) .744	(36.60) 1.441
49*†	(22.90) .902	(43.80) 1.724
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071
70†	(26.90) 1.059	(60.60) 2.386
80†	(26.90) 1.059	(68.60) 2.701
100†	(26.90) 1.059	(84.60) 3.331

Positions where no dimensions are given do not have keying feature.
* Mates with ECDP Series.
† Availavle with –01 Card Only.



10, 20 & 30

Due to technical progress, all designs, specifications and components are subject to change without notice.